

AMENDMENTS TO THE SPECIFICATION:

Page 16, replace the paragraph beginning on line 17 and bridging pages 16 and 17 with the following amended paragraph:

--The V-groove 15 is so formed that an inner wall on the side of the semiconductor laser chip ~~[[10]]~~ 11 is formed as an inclined plane 15a with its left side downward. The ball lens 14 is so arranged in the V-groove 15 that a part 14a of the lower-half spherical face of the ball lens 14 contacts the inclined plane 15a so as to be positioned and mounted in the V-groove 15. Therefore, the ball lens 14 is fixed to the heat sink 13 with a stable position in such a manner that it is supported by the opposing V-shaped bottom 15b of the V-groove 15, and a part 14a of the lower-half spherical surface is supported by the inclined plane 15a. In order to fix the ball lens 14 to the heat sink 13, a UV adhesive, a low-melting glass, a solder or the like may be used. With this mounting structure, the semiconductor laser chip 11 and the collimator lens 14 are so positioned that the laser beam output from the semiconductor laser chip 11 is made incident on a surface of the collimator lens at a position inside of the focal point of the collimator lens 14, and the respective components are integrated into the non-conductive heat sink so as to form a unit.--